



DOCKET NO. EN995064BVUS4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Papathomas *et al.*

) Examiner: Berman, S

Serial No.: 09/771,275

) Art Unit: 1711

Filed: 01/26/01

)

For: **LEAD PROTECTIVE COATING COMPOSITION, PROCESS AND
STRUCTURE THEREOF**

Commissioner for Patents
Washington D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to initial examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend claims 13, 15 and 20.

Sub D1
~~13. (TWICE AMENDED) A method for encapsulating a solder joint between an integrated circuit chip and a substrate, comprising the steps of:~~

~~forming a composition that includes a cyanate ester, a photoinitiator, and a coefficient of thermal expansion reducing dispersed filler;~~

~~applying an amount of the composition at a thickness sufficient to cover substantially all of the solder joint; and~~

~~photocuring the composition to reinforce the solder joint.~~

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